

# SOT1976-1

VFBGA115, very thin, fine-pitch ball grid array package, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

4 January 2019

Package information

## 1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA115
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	18-05-2018
Manufacturer package code	98ASA01229D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
package height	-	0.86	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	115	-	



VFBGA115, very thin, fine-pitch ball grid array package, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

2 Package outline

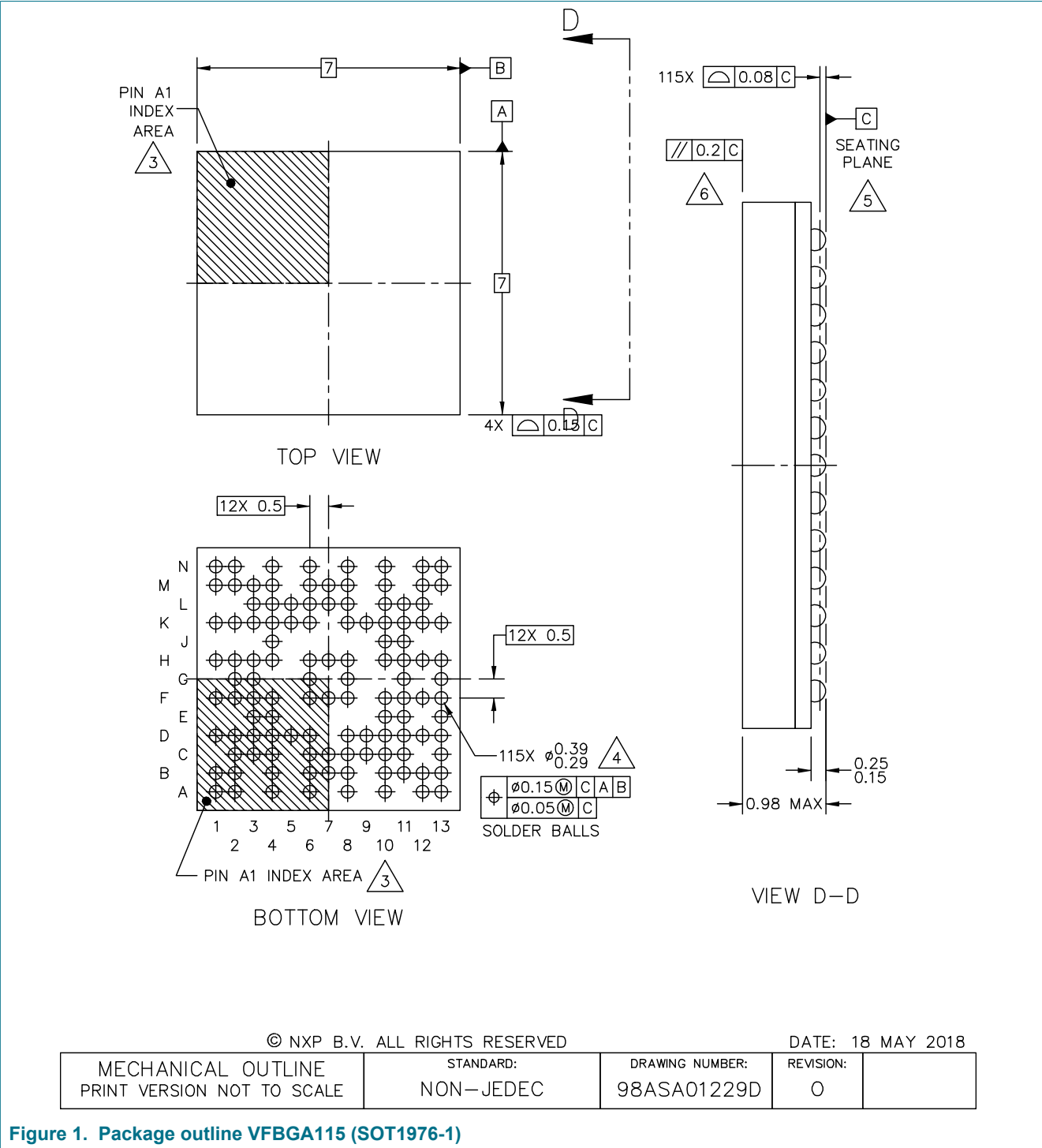
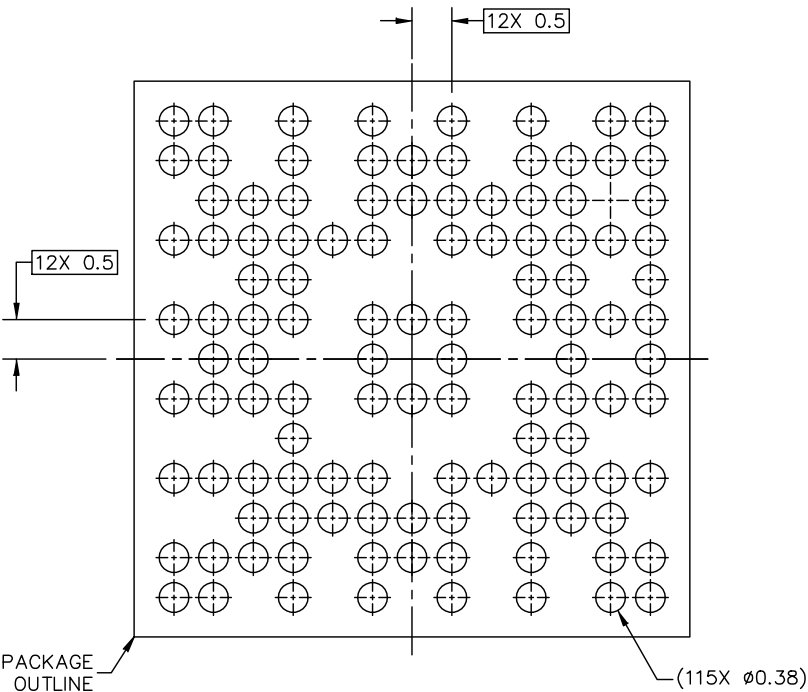


Figure 1. Package outline VFBGA115 (SOT1976-1)

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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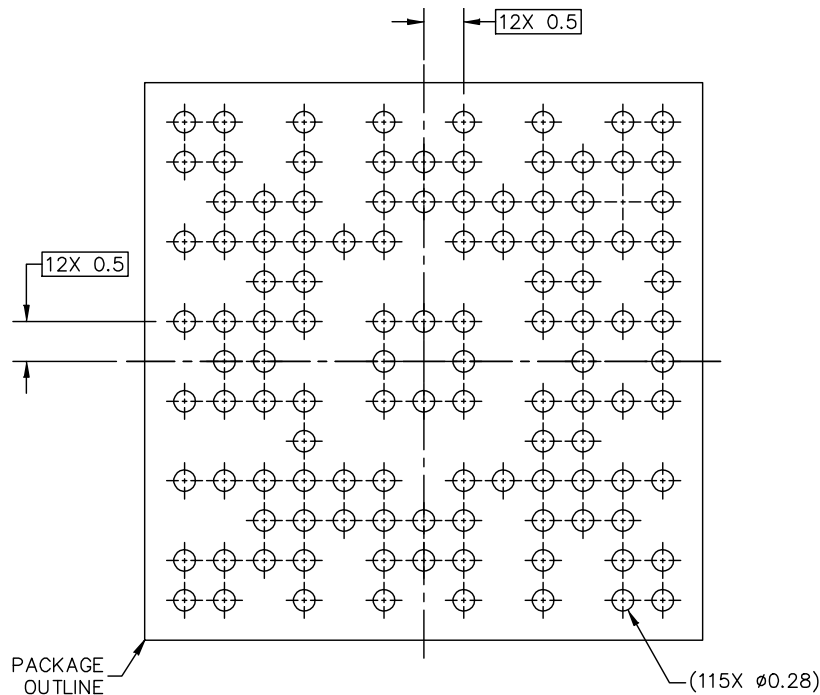
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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01229D	REVISION: O	
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Figure 2. Reflow soldering footprint part1 for VFGBA115 (SOT1976-1)

VFBGA115, very thin, fine-pitch ball grid array package, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

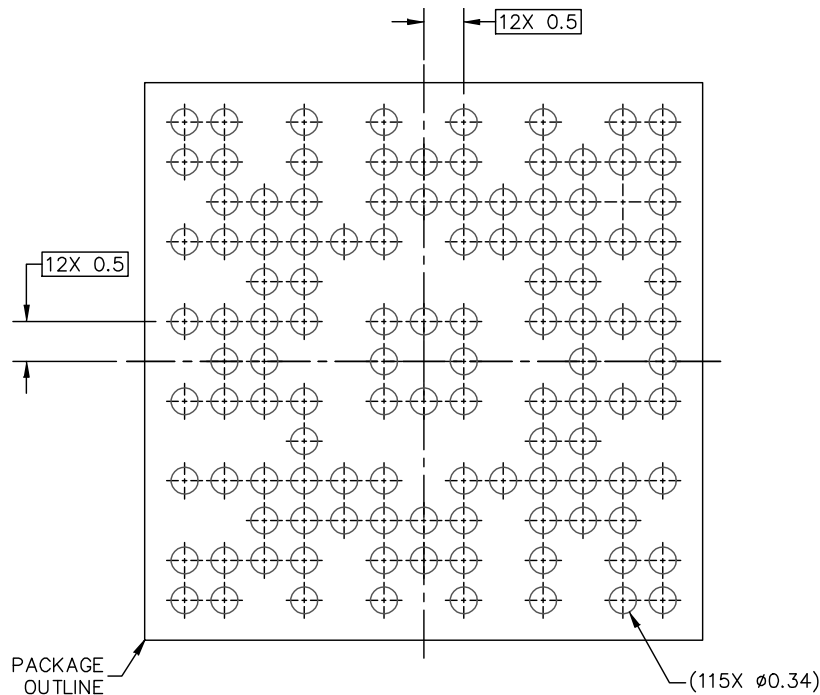
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Figure 3. Reflow soldering footprint part2 for VFBGA115 (SOT1976-1)



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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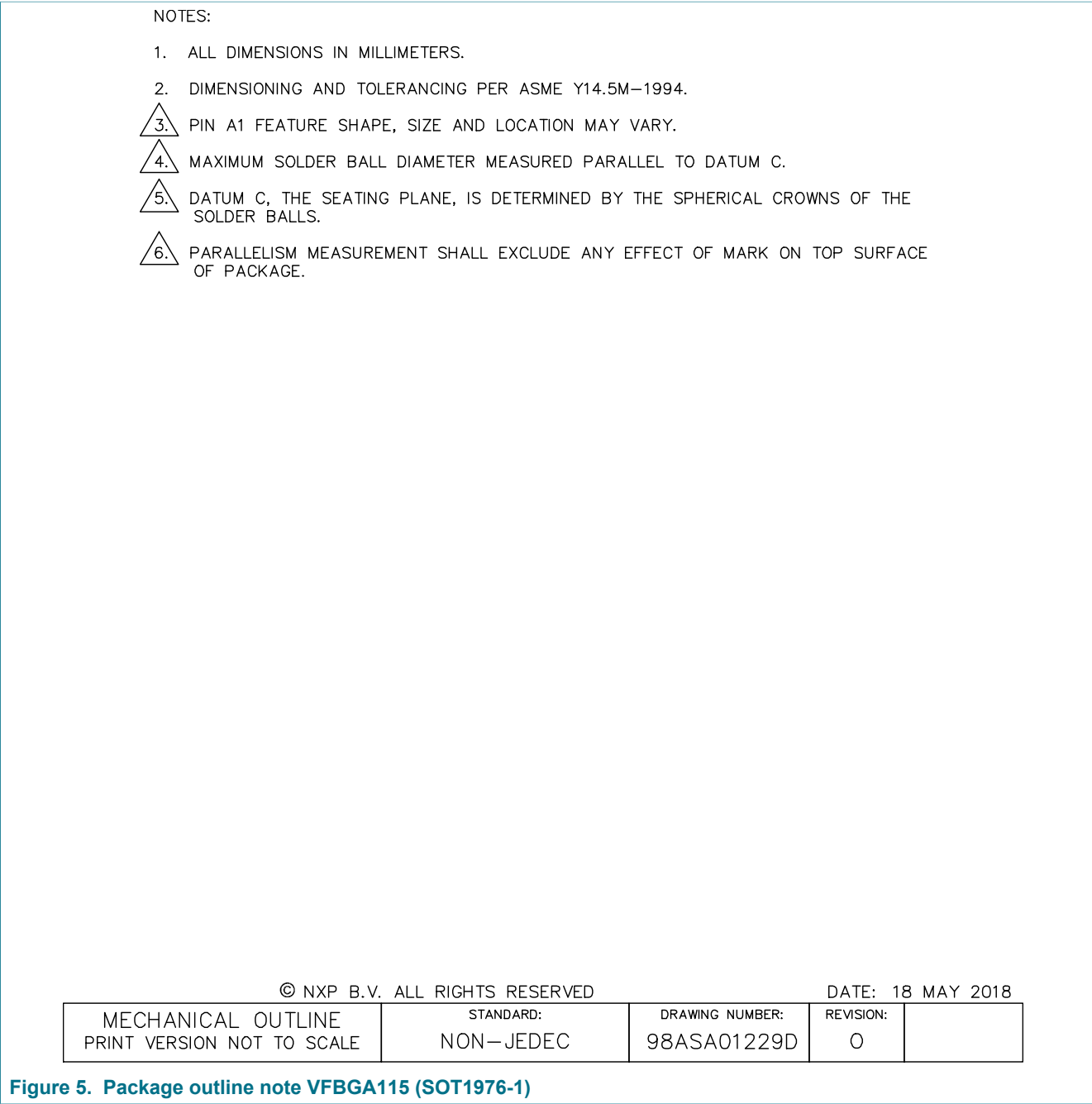
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Figure 4. Reflow soldering footprint part3 for VFPGA115 (SOT1976-1)

VFBGA115, very thin, fine-pitch ball grid array package, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body



## 4 Legal information

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